

DOCKET NO.: 93-C-077C2  
CLIENT NO.: STMI01-93077  
CUSTOMER NO.: 30425

PATENT  
DIVISION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: : LOI NGUYEN ET AL.  
Serial No. : 09/712,827  
Filed : November 14, 2000  
For : METHOD AND INTERLEVEL DIELECTRIC STRUCTURE  
FOR IMPROVED METAL STEP COVERAGE  
Group No. : 2814  
Examiner : Long Pham

Mail Stop 16  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

BEST AVAILABLE COPY

Sir:

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

The undersigned hereby certifies that the following documents:

1. Request for Refund;
2. Copy of Petition Under § 1.181(a)(3) as filed on January 15, 2004 and a copy of the return date-stamped postcard;
3. Copy of Information Disclosure Statement as filed on March 27, 2001 and a copy of the return date-stamped postcard;
4. Copy of Deposit Account Statement dated July 2004; and
5. A return postcard

relating to the above application, were deposited as "First Class Mail" with the United States Postal Service, addressed to Mail Stop 16, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on December 23, 2004.

Date: 12/23/04

Date: Dec. 22, 2004

*Nancy J. Todd*  
\_\_\_\_\_  
Mailer

*William A. Munck*  
\_\_\_\_\_  
William A. Munck

Reg. No. 39,308

P.O. Drawer 800889  
Dallas, Texas 75380  
Phone: (972) 628-3600  
Fax: (972) 628-3616  
E-mail: [wmunck@davismunck.com](mailto:wmunck@davismunck.com)

BEST AVAILABLE COPY

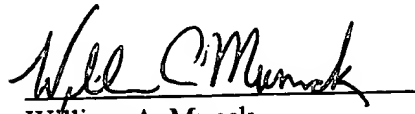
ATTORNEY DOCKET NO.: 93-C-077C1  
U.S. SERIAL NO.: 09/712,827  
PATENT

Please issue a credit in the amount of \$180.00 to Davis Munck Deposit Account No. 50-0208  
for this overpayment.

Respectfully submitted,

DAVIS MUNCK, P.C.

Date: Dec 22, 2004

  
William A. Munck  
Registration No. 39,308

P.O. Drawer 800889  
Dallas, Texas 75380  
Tel: (972) 628-3600  
Fax: (972) 628-3616  
E-mail: [wmunck@davismunck.com](mailto:wmunck@davismunck.com)



**United States  
Patent and  
Trademark Office**

**BEST AVAILABLE COPY**



**Deposit Account Statement**

**Requested Statement Month:**

July 2004

**Deposit Account Number:**

500208

**Name:**

DAVIS MUNCK

**Attention:**

JOHN T MOCKLER

**Address:**

900 THREE GALLERIA TOWER

**City:**

DALLAS

**State:**

TX

**Zip:**

75240

DATE	SEQ	POSTING REF TXT	ATTORNEY DOCKET NBR	FEE CODE	AMT	BAL
07/02	5	10037180	P05023	1501	\$1,330.00	\$4,180.00
07/02	6	10037180	P05023	8001	\$30.00	\$4,150.00
07/07	148	10881098	STMI01-03139	1001	\$770.00	\$3,380.00
07/08	1	10882690	04-L-014	1001	\$770.00	\$2,610.00
07/08	2	10882690	04-L-014	1201	\$86.00	\$2,524.00
07/08	139	10610373	16217RRUS01U	8007	\$20.00	\$2,504.00
07/08	141	10610517	15995RRUS01	8007	\$20.00	\$2,484.00
07/08	163	10610515	15993RRUS01	8007	\$20.00	\$2,464.00
07/08	164	10610511	15996RRUS01U	8007	\$20.00	\$2,444.00
07/19	56	E-REPLENISHMENT		9203	-\$3,500.00	\$5,944.00
07/29	4	09712827	STMI01-93077	1806	\$180.00	\$5,764.00
07/29	39	09992500	P04950	1201	-\$172.00	\$5,936.00
07/29	40	09992500	P04950	1202	-\$180.00	\$6,116.00
07/30	72	09896796	RFMI01-00001	8011	\$55.00	\$6,061.00
07/30	104	10659907	2003.09.007.WSO	8007	\$20.00	\$6,041.00
07/30	108	10696502	2003.10.004.WSO	8007	\$20.00	\$6,021.00
07/30	137	10703700	2003.10.019.WSO	8007	\$20.00	\$6,001.00
07/30	219	09729853	CRAN01-00266	8010	\$25.00	\$5,976.00
07/30	220	09729853	CRAN01-00266	8008	\$200.00	\$5,776.00

START  
BALANCE  
\$5,510.00

SUM OF  
CHARGES  
\$3,586.00

SUM OF  
REPLENISH  
BALANCE  
\$3,852.00 \$5,776.00

**Need Help? | Return to USPTO Home Page | Return to Finance Online Shopping**

BEST AVAILABLE COPY

Mailed:

Jan. 15, 2004

In re. Application of: Loi N. Nguyen, et al

Serial No.: 09/712,827

Filing Date: November 14, 2000

Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR  
IMPROVED METAL STEP COVERAGE

Docket No.: 93-C-077C1 (STMI01-93077)

The following documents were received in the U.S. Patent and Trademark Office on the  
date stamped below:

- 1) Certificate of Mailing by First Class Mail; and,
- 2) Petition Under 37 C.F.R. §1.181.



DOCKETED  
JAN 30 2004

RECEIVED

JAN 28 2004

DAVIS MUNCK

**BEST AVAILABLE COPY**

Mailed:

Jan. 15, 2004

In re. Application of: Loi N. Nguyen, et al

Serial No.: 09/712,827

Filing Date: November 14, 2000

Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR  
IMPROVED METAL STEP COVERAGE

Docket No.: 93-C-077C1 (STMI01-93077)

The following documents were received in the U.S. Patent and Trademark Office on the  
date stamped below:

- 1) Certificate of Mailing by First Class Mail; and,
- 2) Petition Under 37 C.F.R. §1.181.

**BEST AVAILABLE COPY**

DOCKET NO. 93-C-077C1 (STMI01-93077)  
Customer No. 30425

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: : Loi N. Nguyen, et al.  
Serial No. : 09/712,827  
Filed : November 14, 2000  
For : METHOD AND INTERLEVEL DIELECTRIC  
STRUCTURE FOR IMPROVED METAL STEP  
COVERAGE  
Group No. : 2814  
Examiner : L. Pham

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATE OF MAILING BY FIRST CLASS MAIL**

Sir:

The undersigned hereby certifies that the following documents:

1. Petition Under 37 C.F.R. §1.181;
2. A postcard receipt;

relating to the above application, were deposited as "First Class Mail" with the United States Postal Service, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 1/15/04.

Date: 1/15/04

Date: 1-15-04

Kathy Cedar  
Mailer  
Daniel E. Venglarik  
Daniel E. Venglarik  
Registration No. 39,409

P.O. Box 802432  
Dallas, Texas 75380  
Phone: (972) 628-3600  
Fax: (972) 628-3616  
E-mail: [dvenglarik@davismunck.com](mailto:dvenglarik@davismunck.com)

**BEST AVAILABLE COPY**

DOCKET NO. 93-C-077C1 (STMI01-93077)  
Customer No. 30425

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: : Loi N. Nguyen, et al.  
Serial No. : 09/712,827  
Filed : November 14, 2000  
For : METHOD AND INTERLEVEL DIELECTRIC  
STRUCTURE FOR IMPROVED METAL STEP  
COVERAGE  
Group No. : 2814  
Examiner : L. Pham

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**PETITION UNDER 37 C.F.R. § 1.181**

Pursuant to 37 C.F.R. § 1.181(a)(3), Applicants respectfully invoke the supervisory authority of the Commissioner with respect to consideration of the references cited by Applicants in an Information Disclosure Statement filed March 27, 2001.

An Information Disclosure Statement was filed by Applicants pursuant to 37 C.F.R. § 1.56 on March 27, 2001. The Information Disclosure Statement was properly filed with a Form PTO-1449 listing all cited references and copies of each reference cited.

BEST AVAILABLE COPY

ATTORNEY DOCKET NO. 93-C077C1 (STMI01-93077)

U.S. SERIAL NO. 09/712,827

PATENT

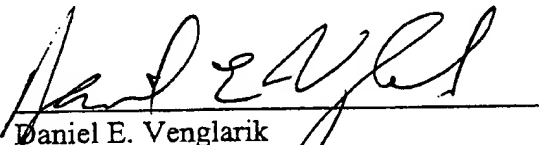
Applicants have unsuccessfully attempted to obtain an initialed Form PTO-1449 for the Information Disclosure Statement indicating consideration of the cited references. Consideration of the cited references and an initialed Form PTO-1449 are respectfully requested.

The Commissioner is hereby authorized to charge any additional fees connected with this communication or credit any overpayment to Deposit Account No. 50-0208.

Respectfully submitted,

DAVIS MUNCK, P.C.

Date: 1-15-04

  
Daniel E. Venglarik  
Registration No. 39,408

P.O. Box 802432  
Dallas, Texas 75380  
Tel: (972) 628-3600  
Fax: (972) 628-3616  
E-mail: [dvenglarik@davismunck.com](mailto:dvenglarik@davismunck.com)



BEST AVAILABLE COPY

Mailed: March 27, 2001  
In re. Application of: Loi N. Nguyen, et al  
Serial No.: 09/712,827  
Filing Date: November 14, 2000  
Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR  
IMPROVED METAL STEP COVERAGE  
Docket No.: 93-C-077C1 (STMI01-93077)

The following documents were received in the U.S. Patent and Trademark Office on the date stamped below:

- 1) Information Disclosure Statement;
- 2) Form PTO-1449; and,
- 3) Eleven (11) references as cited on Form PTO-1449.



DOCKETED  
APR 08 2001

RECEIVED  
APR - 4 2001  
NOVAKOV DAVIS & MUNCK

BEST AVAILABLE COPY

Mailed: March 27, 2001  
In re. Application of: Loi N. Nguyen, et al  
Serial No.: 09/712,827  
Filing Date: November 14, 2000  
Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR  
IMPROVED METAL STEP COVERAGE  
Docket No.: 93-C-077C1 (STMI01-93077)

The following documents were received in the U.S. Patent and Trademark Office on the date stamped below:

- 1) Information Disclosure Statement;
- 2) Form PTO-1449; and,
- 3) Eleven (11) references as cited on Form PTO-1449.

**BEST AVAILABLE COPY**

**DOCKET NO. 93-C-077C1 (STMI01-93077)**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of : Loi N. Nguyen, et al.  
U.S. Serial No. : 09/712,827  
Filed : November 14, 2000  
For : METHOD AND INTERLEVEL DIELECTRIC STRUCTURE  
FOR IMPROVED METAL STEP COVERAGE  
Group No. : 2835  
Examiner : (Not Yet Known)

Commissioner of Patents  
and Trademarks  
Washington, D. C. 20231

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 3/27/01 (Date)

KATHY LONGNECKER  
(Printed or typed name of person signing the certificate)  
Kathy Longnecker  
(Signature of the person signing the certificate)

Dear Sir:

**INFORMATION DISCLOSURE STATEMENT**

Pursuant to the duty of disclosure under 37 C.F.R. § 1.56, Applicant submits this statement. This submittal is made in accordance with 37 C.F.R. §§ 1.97 and 1.98 and § 609 of the Manual of Patent Examining Procedure. The patents, publications and other information herein are listed below and on the attached Form PTO-1449. Copies of the listed references are submitted herewith.

# BEST AVAILABLE COPY

DOCKET NO. 93-C-077C1 (STMI01-93077)  
U.S. SERIAL NO. 09/712,827  
PATENT

<u>U.S. Patent No.</u>	<u>Inventor</u>	<u>Date</u>
4,686,000	Heath	Aug. 11, 1987
4,824,767	Chambers, et al.	Apr. 25, 1989
5,063,176	Lee, et al.	Nov. 5, 1991
5,166,088	Ueda, et al.	Nov. 24, 1992
5,266,516	Ho	Nov. 30, 1993

<u>Foreign Patent No.</u>	<u>Country</u>	<u>Date</u>
JP60246675	Japan	December 6, 1985
JP4196486	Japan	July 16, 1992
0 523 856 A2	Europe	January 20, 1993
JP5074958	Japan	March 26, 1993
0 534 130 A1	Europe	March 31, 1993

## Publications

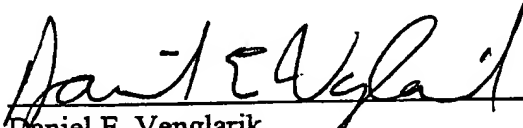
"VLSI Fabrication Principles," by Sorab K. Ghandhi, Rensselaer Polytechnic Institute, A Wiley-Interscience Publication, 1983, pages 479-482; 499-501.

Applicant hereby expressly reserves the right to swear behind the effective dates of any of the above Patents and to question the relevance and materiality of the Patents and Publications listed herein, in whole, in part, or in combination, subsequent to filing this Information Disclosure Statement.

Respectfully submitted,

NOVAKOV DAVIS & MUNCK, P.C.

Date: 3-27-01

  
Daniel E. Venglarik  
Registration No. 39,409

**BEST AVAILABLE COPY**

**DOCKET No. 93-C-077C1 (STMI01-93077)**  
**U.S. SERIAL No. 09/712,827**  
**PATENT**

900 Three Galleria Tower  
13155 Noel Road  
Dallas, Texas 75240  
Telephone: (214) 922-9221  
Facsimile: (214) 969-7557  
*email: [dvenglarik@novakov.com](mailto:dvenglarik@novakov.com)*

# BEST AVAILABLE COPY

Sheet 1 of 1

FORM PTO-1449 (REV. 7.80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 93-C-077C1 (STMI01-93077)		SERIAL NO. 09/712,827	
<b>LIST OF REFERENCES CITED BY APPLICANT</b> (Use several sheets if necessary)				APPLICANT Loi N. Nguyen, et al.			
				FILING DATE November 14, 2000		GROUP 2835	
<b>U. S. PATENT DOCUMENTS</b>							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)
	AA	4,686,000	08/11/1987	Heath	156	643	Feb. 19, 1986
	AB	4,824,767	04/25/1989	Chambers, et al.	430	313	Jun. 2, 1987
	AC	5,063,176	11/05/1991	Lee, et al.	437	195	May 30, 1990
	AD	5,166,088	11/24/1992	Ueda, et al.	437	47	Jun. 25, 1991
	AE	5,266,516	11/30/1993	Ho	437	57	Jan. 2, 1992
	AF						
	AG						
<b>FOREIGN PATENT DOCUMENTS</b>							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES    NO
	AH	0 523 856 A2	06/28/91	Europe			
	AI	0 534 130 A1	3/31/93	Europe			
	AJ	JP60246675	06/12/85	Japan			
	AK	JP4196486	07/16/92	Japan			
	AL	JP5074958	03/26/93	Japan			
	AM						
<b>OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
	AN	"VLSI Fabrication Principles," by Sorab K. Ghandhi, Rensselaer Polytechnic Institute, A Wiley Publication, John Wiley & Sons, 1983, pages 479-482, 499-501.					
	AO						
	AP						
EXAMINER					DATE CONSIDERED		
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line if not in conformance and not considered. Include copy of this form with next communication to applicant.							

**BEST AVAILABLE COPY**



**DOCKET NO. 93-C-077C1 (STMI01-93077)**  
**Customer No. 30425**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: : Loi N. Nguyen, et al.  
Serial No. : 09/712,827  
Filed : November 14, 2000  
For : **METHOD AND INTERLEVEL DIELECTRIC  
STRUCTURE FOR IMPROVED METAL STEP  
COVERAGE**  
Group No. : 2814  
Examiner : L. Pham

**Commissioner for Patents**

7/29/2004 P.O. Box 1450  
1 FC:1806 Alexandria, VA 22313-1450

Sir:

**PETITION UNDER 37 C.F.R. § 1.181**

Pursuant to 37 C.F.R. § 1.181(a)(3), Applicants respectfully invoke the supervisory authority of the Commissioner with respect to consideration of the references cited by Applicants in an Information Disclosure Statement filed March 27, 2001.

An Information Disclosure Statement was filed by Applicants pursuant to 37 C.F.R. § 1.56 on March 27, 2001. The Information Disclosure Statement was properly filed with a Form PTO-1449 listing all cited references and copies of each reference cited.

Adjustment date: 02/08/2005 SDIRETA1  
07729/2004 GSTANLEY 00000003 500208 09712827  
01 FC:1806 180.00 CR